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AMENDMENTS TO CLAIMS

1. (Currently amended) A method for collecting temperature data in a computer facility including wherein the facility includes a plurality of computer systems, the method comprising:

coupling a plurality of sensors to at least one each of the computer systems at locations that allow cooling requirements of the facility to be determined; and;

connecting each of the plurality of sensors to a central system, [[; and]]

utilizing the central system to collect temperature data from each of the plurality of sensors.

Claim 2 (Cancelled)

3. (Original) The method of claim 1 wherein coupling a plurality of sensors to at least one of the systems further comprises:

connecting each of the plurality of sensors to the at least one of the systems via a flexible stalk.

Claims 4-7 (Cancelled)

8. (Currently amended) The method of claim [[5]] 31 wherein each temperature collection module includes the central system includes an embedded control for and the embedded controller is utilized to periodically [[query]] querying the plurality of sensors to [[and]] create an ambient temperature profile.

Claims 9-10 (Cancelled)

11. (Withdrawn) A system for collecting temperature data in a data center wherein the data center includes a plurality of racks of systems comprising: at least one plurality of sensors coupled to the at least one of the rack of systems; means for connecting the at least one plurality of sensors to a central system; and means for

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utilizing the central system to collect temperature data from the at least one plurality of sensors.

12. (Withdrawn) The system of claim 11 wherein each of the plurality of sensor is coupled to the at least one of the rack of systems via a flexible stalk.

13. (Withdrawn) The system of claim 11 wherein the means for connecting the at least one plurality of sensors to a central system comprises an electromechanical connector.

14. (Withdrawn) The system of claim 11 wherein the plurality of sensors comprises 8 sensors.

15. (Withdrawn) The system of claim 13 wherein the electro-mechanical connector comprises a connector board.

16. (Withdrawn) The system of claim 15 wherein the connector board includes at least one RJ-11 type connector.

17. (Withdrawn) The system of claim 16 wherein the means for utilizing the central system to collect temperature data from the at least one plurality of sensors further comprises: means for periodically querying the plurality of sensors to collect temperature data related to the at least one rack of systems; and means for creating an ambient temperature profile of the data center based on the temperature data.

18. (Withdrawn) A data center comprising: at least one rack of systems; at least one plurality of sensors coupled to the at least one rack of systems; at least one electromechanical connector coupled to the at least one plurality of sensors; and a central computer system coupled to the at least one electro-mechanical connector for collecting temperature data related to the at least one rack of systems.

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19. (Withdrawn) The data center of claim 18 wherein each of the plurality of sensor is coupled to the at least one of the rack of systems via a flexible stalk.

20. (Withdrawn) The data center of claim 18 wherein the at least one electromechanical connector comprises a connector board.

21. (Withdrawn) The data center of claim 18 wherein the plurality of sensors comprises 8 sensors.

22. (Withdrawn) The data center of claim 18 wherein the central computer system includes logic for: periodically querying the plurality of sensors to collect temperature data related to the at least one rack of systems; and creating a temperature profile of the data center based on the temperature data.

23. (Withdrawn) The data center of claim 20 wherein the connector board includes at least one RJ-11 type connector.

Claims 24-26 (Cancelled)

27. (Withdrawn) A temperature collection module for collecting temperature data in a data center wherein the data center includes a plurality of racks of systems comprising. a first set of interface electronics for interfacing with a plurality of sensors coupled to at least one of the plurality of racks of systems; temperature collection logic coupled to the first set of interface electronics for collecting temperature data from the plurality of racks of systems; and a second set of interface electronics coupled the temperature collection logic for interfacing with a central computer system.

28. (Withdrawn) The module of claim 27 wherein the temperature collection logic further comprises logic for: querying of each of the sensors in the data center; providing an initiation command; reading the measured temperature of each of the sensors; and generating a temperature profile of the data center based on the temperature readings.

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29. (Withdrawn) The module of claim 28 wherein the temperature profile includes a variety of profiles based on varying locations of the sensors.

30. (New) The method of claim 1, wherein each computer system includes a computer rack; wherein coupling the sensors includes coupling multiple sensors to each rack; and wherein connecting the sensors includes connecting each rack of sensors to a dedicated bus, connecting each bus to a temperature collection module, and connecting the module to the central system.

31. (New) The method of claim 1, wherein the computer systems are arranged in multiple rows of racks, wherein a dedicated temperature collection module and a dedicated sensor bus are provided for each row; wherein coupling the sensors includes coupling multiple sensors to each row of racks; and wherein connecting the sensors includes connecting each row of sensors to its dedicated module via its dedicated bus, and connecting each module to the central system.

32. (new) The method of claim 31, wherein the substations are connected to the central system via an Ethernet connection.

33. (New) The method of claim 31, further comprising identifying the sensors to their dedicated temperature collection modules.

34. (New) The method of claim 30, wherein the dedicated buses are 1-wire buses.

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35. (New) A method for collecting temperature data in a facility including a plurality of systems, the method comprising:

- coupling a plurality of sensors to each of the systems;
- grouping the systems into multiple groups, each group having a dedicated one-wire bus and a dedicated temperature collection module;
- connecting each group of sensors to its dedicated module via its dedicated one-wire bus; and
- connecting each temperature collection module to a central processing system.